Session 10C — IP Session: System-in-Package Design and Test Practices

Organizers: Yervant Zorian (Virage Logic) and Bruce Kim (University of Alabama)

Today’s system-in-package (SiP) technology involves the system integration of multiple die from various technologies into a common package. This session will present SiP applications and their design and test practices from the major SiP companies. The presentations include discussions in standardized test flows, chip-package co-design issues for SiP, and trade-offs between SiP vs. POP vs. SOC integration for cell phone applications.

Presentations:

System-in-Package Test: Problems, Practices and Solutions
Davide Appello, ST Microelectronics

Schematic Based Chip/Package Co-design Flow for Mixed-Signal System-in-Package Designs
Thomas Brandtner, Infineon

SoC Integration — SIP vs. SOC vs. POP
Peter Rickert, Texas Instruments